

**PHOTOSENSITIVE RESIN COMPOSITION, PHOTOSENSITIVE ELEMENT USING THE SAME, METHOD FOR PRODUCING RESIST PATTERN AND METHOD FOR PRODUCING PRINTED WIRING BOARD**

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**Abstract of JP2002182381**

**PROBLEM TO BE SOLVED:** To provide a photosensitive resin composition excellent in adhesion and resolution, suppressing the occurrence of scum and useful to increase the density of a printed wiring board and to provide a photosensitive element, a method for producing a resist pattern and a method for producing a printed wiring board.

**SOLUTION:** The photosensitive resin composition contains (A) a binder polymer, (B) a compound of formula (I) (where R1 is H or methyl; X1 is a 2-6C alkylene; (m) is an integer of 4-20; and (n) is an integer of 1-15) and (C) a photopolymerization initiator. The photosensitive element uses the photosensitive resin composition. In the method for producing a printed wiring board, the method for producing a resist pattern is adopted.

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